

### **SURFACE MOUNT SCHOTTKY BARRIER RECTIFIERS**

REVERSE VOLTAGE: 20 to 200 VOLTS FORWARD CURRENT: 1.0 AMPERE

#### **Features**

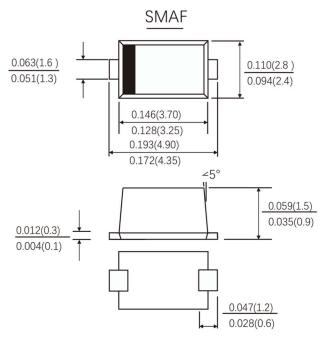
- Plastic package has Underwriters Laboratory
  Flammability Classification 94V-O
- Metal silicon junction, majority carrier conduction
- Low power loss, high efficiency
- For surface mounted applications
- High current capability, Low forward voltage drop
- High temperature soldering guaranteed: 260°C/10 seconds at terminals
- Component in accordance to RoHS 2015/863/EU

## Mechanical Data

■ Case: SMAF molded plastic body

 Terminals: Solder plated, solderable per MIL-STD-750, method 2026 guaranteed

■ Tape Reel: 3000pcs



Dimensions in inches and (millimeters)

## **Maximum Ratings and Electrical Characteristics**

Ratings at 25°C ambient temperature unless otherwise specified. Single phase, half wave, 60HZ, resistive or inductive load. For capacitive load, derate current by 20%.

Parameters / Marking Code		Symbols	SS12S	SS13S	SS14S	SS16S	SS110S	SS115S	SS120S	Units
Maximum repetitive peak reverse voltage		VRRM	20	30	40	60	100	150	200	Volts
Maximum RMS voltage		VRMS	14	21	28	42	71	105	140	Volts
Maximum DC blocking voltage		VDC	20	30	40	60	100	150	200	Volts
Maximum average forward rectified current (See Fig. 1)		I(AV)	1.0							Amp
Peak forward surge current 8.3ms single half sine-wave superimposed on rated load (JEDEC method)		IFSM	40.0							Amps
Maximum instantaneous forward voltage at 1.0 A(note 1)		VF	0.55 0.75			0.85	0.90	0.95	Volts	
Maximum instantaneous reverse current at rated DC blocking voltage(Note 1)	T)=25°C		100				20			μΑ
	Tj=100°C	IR	5.0				-			mA
	T)=125°C		-				3.0			
Typical thermal resistance (Note 2) Junction-Abient Junction-Mount		RÐJA RÐJM	150 15							°C/W
Operating junction temperature range		TJ	-55 to+150							°C
Storage temperature range		TSTG	-55 to+150							°C

#### NOTES:

- 1. Pulse test: 300µs pulse width, 1% duty cycle
- 2.Thermal resistance junction-to-ambient to follow JEDEC51-2A, device mounted on FR4 PCB, 2 oz., standard footprint Thermal resistance junction-to-mount to follow JEDEC51-14 transient dual interface test method (TDIM)



## **SS12S THRU SS120S**

## **RATINGS AND CHARACTERISTIC CURVES**

#### FIG.1-FORWARD CURRENT DERATING CURVE

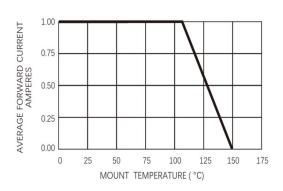
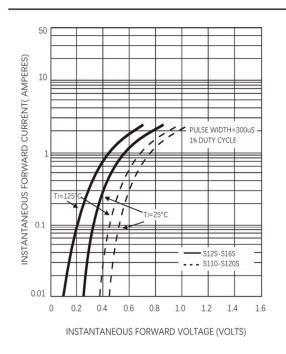
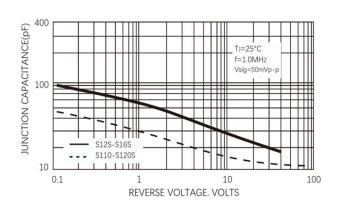


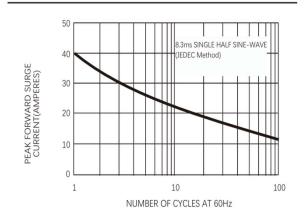
FIG.3-TYPICAL INSTANTANEOUS FORWARD CHARACTERISTICS



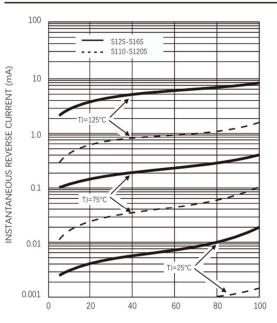
### FIG.5-TYPICAL JUNCTION CAPACITANCE



# FIG.2-MAXIMUM NON-REPETITIVE PEAK FORWARD SURGE CURRENT



#### FIG.4-TYPICAL REVERSE CHARACTERISTICS



PERCENT OF RATED PEAK REVERSE VOLTAGE%